

IRL3402-VB Datasheet N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	
20	0.004@ V _{GS} = 4.5 V	100	
20	0.005@ V _{GS} = 2.5 V	95	

TO-220AB

Top View

FEATURES



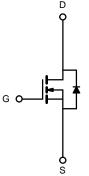
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- OR-ing
- Server
- DC/DC

 P_{D}

T_J, T_{stg}



125^a

-55 to 175

			S	
			N-Channel MOSFET	
ABSOLUTE MAXIMUM RAT	INGS (T _C = 25°C UNL	ESS OTHERWIS	E NOTED)	
Paramete	er	Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	20	V
Gate-Source Voltage		V _{GS}	±12	
Continuous Drain Current (T _{.1} = 175°C)	T _C = 25°C	I _D	100	
Continuous Diam Current (1) = 175 C)	T _C = 100°C		85	
Pulsed Drain Current		I _{DM}	260	^
Avalanche Current		I _{AR}	35	
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	45	mJ

T_C = 25°C

THERMAL RESISTANCE RATINGS					
Paramete	1	Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40		
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	62.5	°C/W	
Junction-to-Case		R _{thJC}	1.25		

Notes:

- See SOA curve for voltage derating.
- b. Duty cycle ≤ 1%.

Power Dissipation

c. When mounted on 1" square PCB (FR-4 material).

Operating Junction and Storage Temperature Range

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1

W

°C



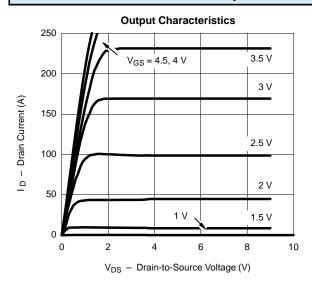
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{DS} = 250 \mu\text{A}$	0.5		1.5	1 '	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = \pm 12 V			±100	nA	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 125°C			50	μΑ	
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 175°C			150	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	120			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}$		0.004			
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 125 ^{\circ}\text{C}$		0.007		Ω	
Diam-Source On-State Resistance	^r DS(on)	$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 175^{\circ}\text{C}$		0.010			
		$V_{GS} = 2.5 \text{ V}, I_D = 20 \text{ A}$		0.005			
Forward Transconductancea	9 _{fs}	$V_{DS} = 5 \text{ V}, I_{D} = 30 \text{ A}$	20			S	
Dynamic ^b			•				
Input Capacitance	C _{iss}			6000			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$		1100		pF	
Reversen Transfer Capacitance	C _{rss}			600		1	
Total Gate Charge ^c	Qg			65	130		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 85 \text{ A}$		13		nC	
Gate-Drain Charge ^c	Q _{gd}			14		1	
Turn-On Delay Time ^c	t _{d(on)}			25	40		
Rise Time ^c	t _r	V_{DD} = 10 V, R_L = 0.12 Ω		120	180	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \approx 85$ A, $V_{GEN} = 4.5$ V, $R_G = 2.5$ Ω		80	120	115	
Fall Time ^c	t _f			100	150		
Source-Drain Diode Ratings a	nd Characteristic	es (T _C = 25°C)b					
Pulsed Current	I _{SM}				240	Α	
Forward Voltage ^a	V _{SD}	$I_F = 100 \text{ A}, V_{GS} = 0 \text{ V}$		1.2	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 50 A, di/dt = 100 A/μs		45	100	ns	

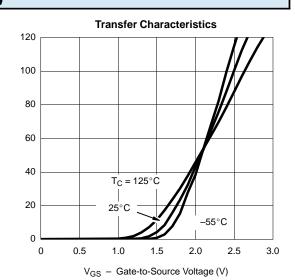
- Notes: a. Pulse test; pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

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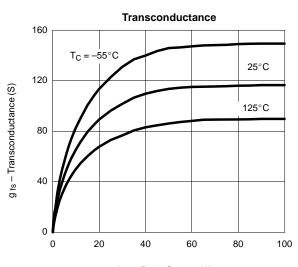
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

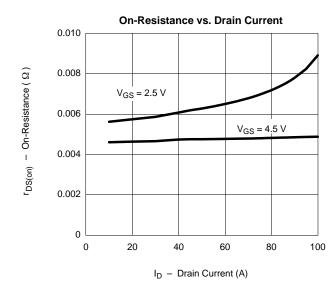


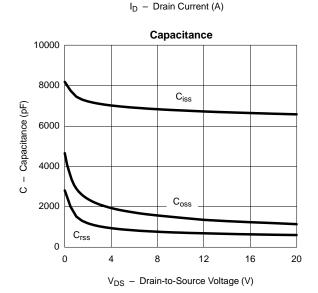


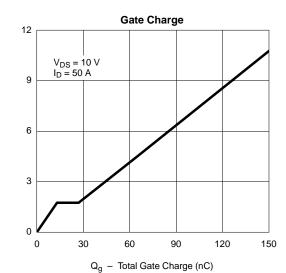
I_D - Drain Current (A)

V_{GS} - Gate-to-Source Voltage (V)



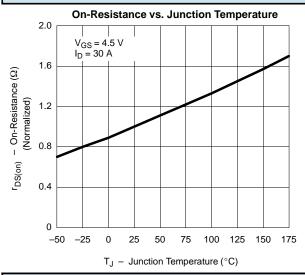


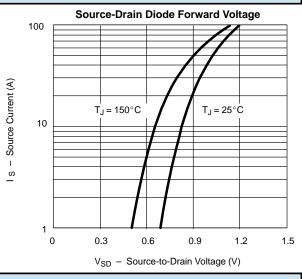






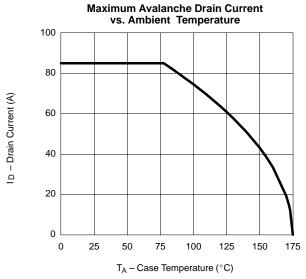
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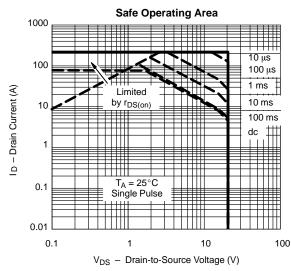


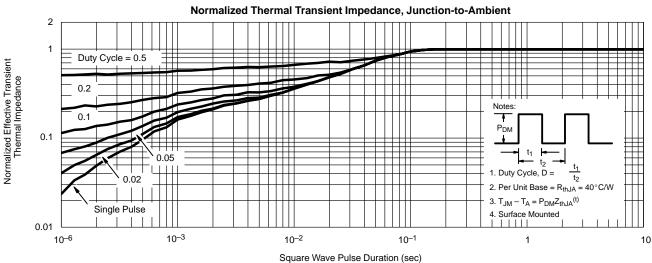


THERMAL RATINGS

4



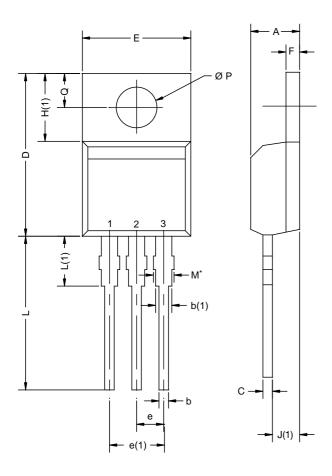




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TO-220AB



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	

DWG: 5471

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

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5



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